

Neoway®有方

N720 Mini PCIe Hardware User Guide

(AUDIO)
Version 1.0



有物联 方智能

GET CONNECTED GET SMART

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This document provides guide for users to use the N720 Mini PCIe (AUDIO).

This document is intended for system engineers (SEs), development engineers, and test engineers.

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1 Overview

N720 is an industrial-grade 4G module developed on Qualcomm platform. This module has an ultra-wide operating temperature range of -40 °C to +85 °C and electrostatic capacity of 8 kV. N720 Mini PCIe complies with the PCI Express Mini Card 1.2 standard and provides various application interfaces in addition to standard interfaces. It is well applicable to video surveillance, notebook, in-vehicle devices, wireless routers, and other IoT terminals with the following features:

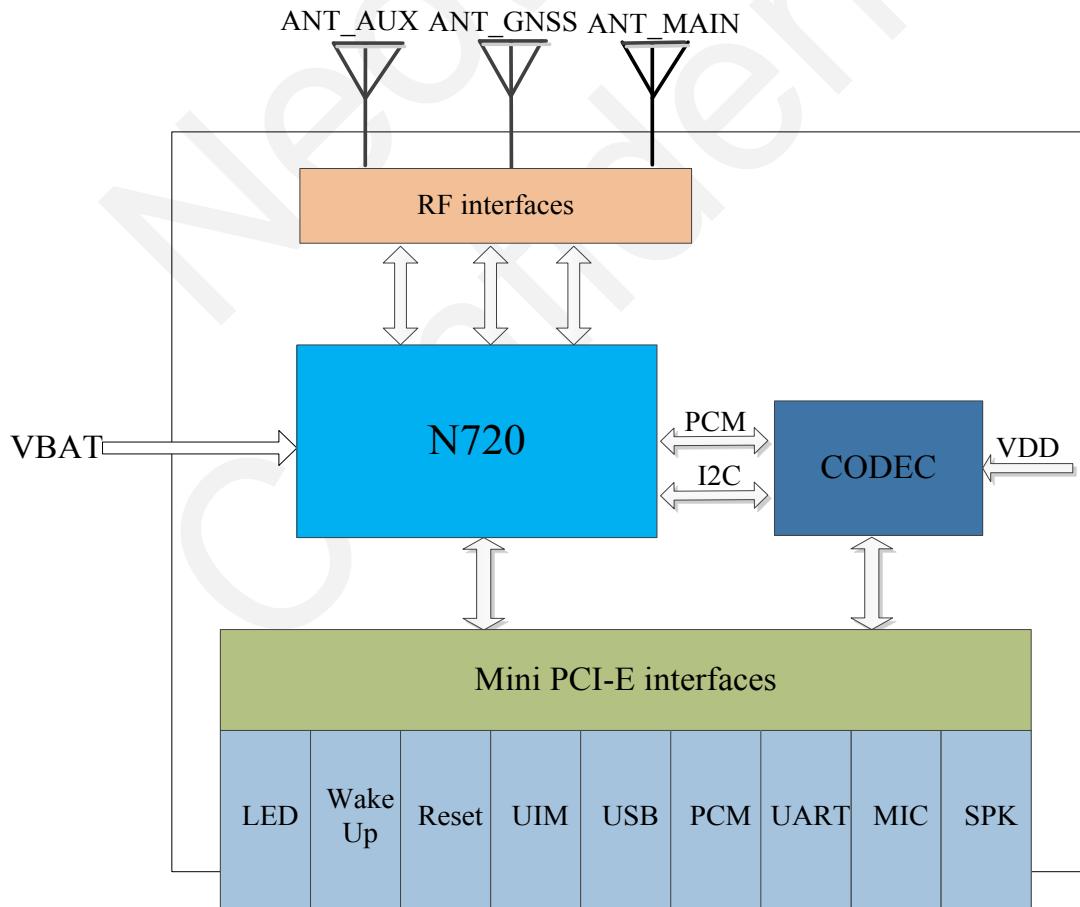
- ARM Cortex-A7 processor, 1.3 GHz main frequency, 256 KB L2 cache, 28 nm process technology
- GSM/GPRS/EDGE & CDMA2000 1x/1xAdvanced/1xEV-DO or A && WCDMA R99 to DC-HSPA+&&TD-SCDMA<E Cat4
- USB2.0/ UIM/ UART/PCM/GNSS/AUDIO

This document describes the block diagram, features, pin description, reference design for application interfaces, mounting packaging, and storage.

1.1 Block Diagram

Figure 1-1 shows the block diagram of N720.

Figure 1-1 N720 Mini PCIe block diagram



1.2 Bands

Mounted N720 modules with different configurations, N720 Mini PCIe series include the following versions to meet the band requirements in different areas:

Module	Version	Area	Category	Band
N720 Mini PCIe	CA	China	Cat4	FDD-LTE: B1, B3, B5, B8 TDD-LTE: B38, B39, B40, B41 TD-SCDMA: B34, B39 UMTS: B1, B8 EV-DO: BC0 CDMA 1x: BC0 GSM/GPRS/EDGE: 900/1800 MHz
	CB	China	Cat4	FDD-LTE: B1, B3, B5, B8 TDD-LTE: B38, B39, B40, B41 TD-SCDMA: B34, B39 UMTS: B1, B8 GSM/GPRS/EDGE: 900/1800 MHz
	CC	China	Cat4	FDD-LTE: B1, B3, B8, B28 TDD-LTE: B38, B39, B40, B41 TD-SCDMA: B34, B39 UMTS: B1, B8 GSM/GPRS/EDGE: 900/1800 MHz
	EA	Europe	Cat4	FDD-LTE: B1, B3, B5, B7, B8, B20 TDD-LTE: B40 UMTS: B1, B8 GSM/GPRS/EDGE: 850/900/1800/1900 MHz
	UA	the United States	Cat4	FDD-LTE: B2, B4, B5, B7, B12, B17 UMTS: B2, B4, B5 GSM/GPRS/EDGE: 850/900/1800/1900 MHz
	JA	Japan	Cat4	FDD-LTE: B1, B3, B8, B9, B19 UMTS: B1, B8, B9, B19
	IA	India	Cat4	FDD-LTE: B3, B5 TDD-LTE: B40 UMTS: B1, B8 GSM/GPRS/EDGE: 850/900/1800/1900 MHz

2 Features

Table 2-1 N720 Mini PCIe baseband and wireless features

Specifications	Description
Power supply	3.0V to 3.6V; Typical value: 3.3 V
Current in sleep mode	<4 mA
Idle current	<25 mA
Operating temperature	-40 °C to +85 °C
Processor	ARM Cortex-A7 processor Main frequency: 1.3 GHz 256 kB L2 cache
Memory	RAM: 256 MB ROM: 256 MB
Band	See Table 2-1.
Rate	GPRS: Max 85.6 Kbps(DL) / Max 85.6 Kbps(UL) CDMA: Max 3.1 Mbps (DL) / Max 1.8 Mbps (UL) WCDMA: DC-HSPA+, Max 42 Mbps(DL)/Max 5.76 Mbps(UL) TD-SCDMA: Max 4.2 Mbps(DL)/Max 2.2 Mbps(UL) FDD-LTE: non-CA cat4, Max 150 Mbps(DL)/Max 50 Mbps(UL) TDD-LTE: non-CA cat4, Max 130 Mbps(DL)/Max 35 Mbps(UL)
Transmit power	GSM850: +33 dBm (Power Class 4) EGSM900: +33 dBm (Power Class 4) DCS1800: +30 dBm (Power Class 1) PCS1900: +30 dBm (Power Class 1) EDGE 850 MHz: +27 dBm (Power Class E2) EDGE 900 MHz: +27 dBm (Power Class E2) EDGE 1800 MHz: +26 dBm (Power Class E2) EDGE 1900 MHz: +26 dBm (Power Class E2) TD-SCDMA:+23 dBm (Power Class 3) CDMA 1X/EVDO:+23 dBm(Power Class 3) UMTS: 23 dBm (Power Class 3) LTE: +23 dBm (Power Class 3)
Antenna feature	2G/3G/4G main antenna, 4G diversity antenna, GNSS antenna, 50 Ω impedance
UART	At most 4 Mbps, 1 groups
UIM	1 group of UIM, 1.8V/3V dual-voltage adaptive
USB	1 group of USB2.0 high-speed interface
PCM	1 group of PCM interface

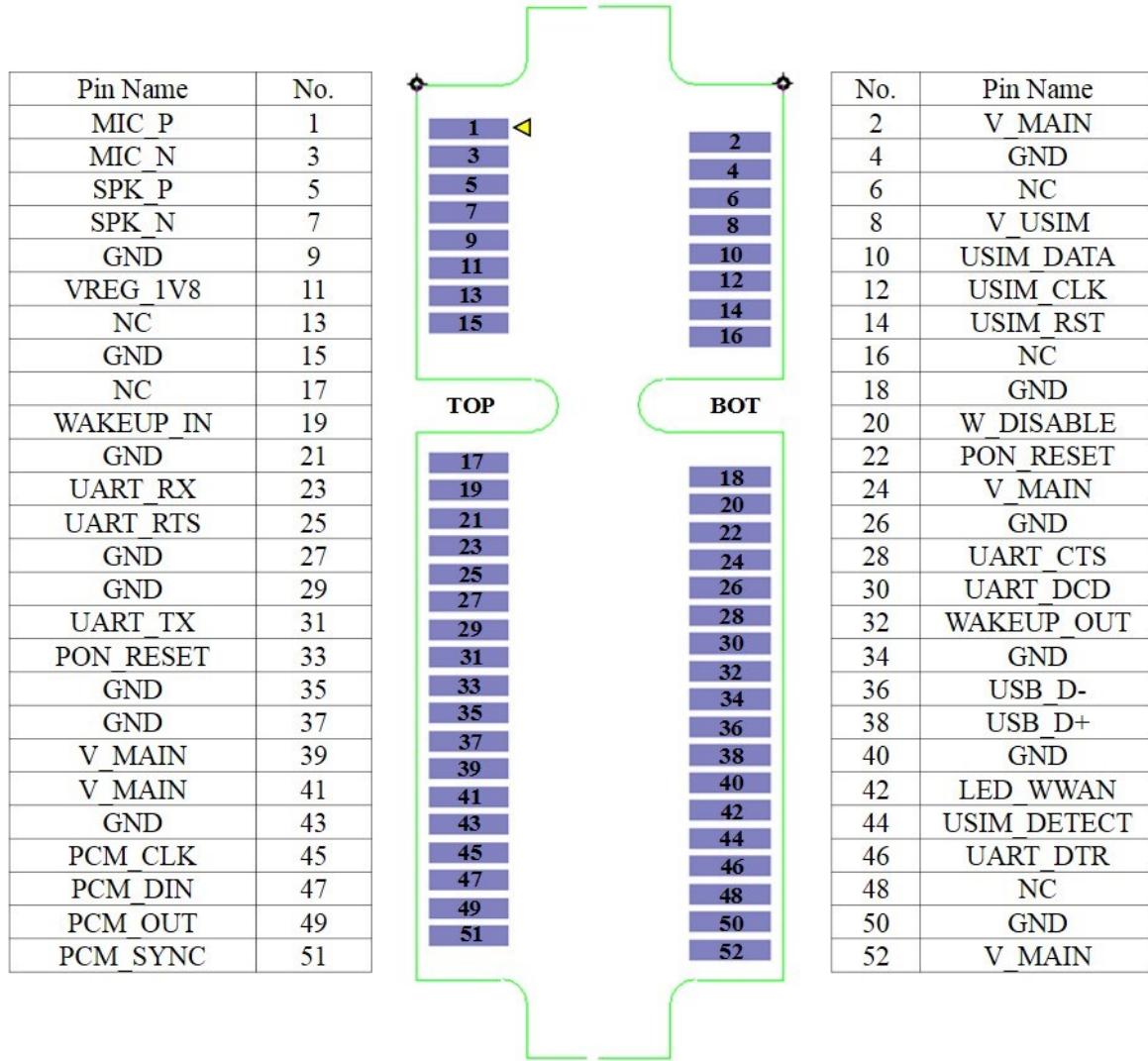
AUDIO	MIC/ SPK differential analog audio interface The I/O volume is adjustable.
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3 Application Interfaces

3.1 Pin Description

N720 Mini PCIe has 52 pins, including general function pins and other pins. Figure 3-1 defines the pins.

Figure 3-1 N720 Mini PCIe pin description





IO: input/output

DI: Digital input

DO: Digital output

PI: Power input

PO: Power output

AI: Analog input

AO: Analog output

OC: Open collector

Table 3-1 N720 Mini PCIe pin description

Name	Pin	I/O	Function	Level Feature (V)	Power Domain	Remarks
Power Supply						
V_MAIN	2, 24, 39, 41, 52	PI	Main power supply	Vmin=3.0 V Vmax=3.6 V Vtyp=3.3 V		Maximum supply current of 3 A peak.
VREG_1P8	11	PO	1.8 V power supply	Vnorm=1.8 V; Imax=50 mA;	1.8 V	Supply power for IO level shifting circuit. Leave this pin unconnected if it is not used.
GND	4, 9, 15, 18 21, 26, 27, 29, 34, 35, 37, 40, 43, 50		GND			
PON RESET	22, 33	DI	Reset input			Low level triggers the reset.
UART						
UART_TX	31	DO	UART data transmit	V _{OL} max=0.45 V; V _{OH} min=1.35 V;	1.8 V	Data transmission
UART_RX	23	DI	UART data receive	V _{IL} min=-0.3 V; V _{IL} max=0.45 V; V _{IH} min=1.35 V; V _{IH} max=2.1 V	1.8 V	Leave these pins unconnected if they are not used.

UART_CTS	28	DI	Clear to send	V_{IL} min=-0.3 V; V_{IL} max=0.45 V; V_{IH} min=1.35 V; V_{IH} max=2.1 V	1.8 V	Leave these pins unconnected if they are not used.
UART_RTS	25	DO	Request to send	V_{OL} max=0.45 V; V_{OH} min=1.35 V	1.8 V	
UART_DTR	46	DI	Data terminal is ready	V_{IL} min=-0.3V; V_{IL} max=0.45V; V_{IH} min=1.35V; V_{IH} max=2.1V	1.8V	Leave this pin unconnected if it is not used.
UART_DCD	30	DO	Data carrier detect	V_{OL} max=0.45V; V_{OH} min=1.35V	1.8V	Leave this pin unconnected if it is not used.
UIM						
V_USIM	8	PO	UIM power supply output	1.8V USIM: $V_{max} = 1.9\text{ V}$; $V_{min} = 1.7\text{ V}$ 3V USIM: $V_{max} = 3.05\text{ V}$; $V_{min} = 2.7\text{ V}$; IO max =50 mA	1.8 V/3 V	Compatible with 1.8/3V UIM card
USIM_RST	14	DO	UIM reset	1.8 V USIM: V_{OL} max = 0.45 V; V_{OH} min = 1.35 V 3 V USIM: V_{OL} max = 0.4 V; V_{OH} min = 2.6V	1.8 V/3 V	

USIM_DATA	10	IO	UIM data input/output	1.8V USIM: $V_{IL\ max} = 0.6\ V$; $V_{IH\ min} = 1.2\ V$; $V_{OL\ max} = 0.45\ V$; $V_{OH\ min} = 1.35\ V$ 3V USIM: $V_{IL\ max} = 0.8\ V$ $V_{IH\ min} = 1.95\ V$ $V_{OL\ max} = 0.45\ V$ $V_{OH\ min} = 2.6\ V$	1.8 V/3 V	
USIM_CLK	12	DO	UIM clock output	1.8 V USIM: $V_{OL\ max} = 0.45\ V$; $V_{OH\ min} = 1.35\ V$ 3V USIM: $V_{OL\ max} = 0.4\ V$ $V_{OH\ min} = 2.6\ V$	1.8 V/3 V	
USIM_DETECT	44	DI	UIM detect	$V_{IL\ min} = -0.3\ V$; $V_{IL\ max} = 0.63\ V$	1.8 V	
USB						
USB_D-	36	IO	Negative signal of USB data	USB2.0		Used for program download and data transmission.
USB_D+	38	IO	positive signal of USB data	USB2.0		Differential traces $90\ \Omega$ impedance
PCM						
PCM_CLK	45	IO	PCM clock signal	$V_{OL\ max}=0.45V$; $V_{OH\ min}=1.35V$	1.8V	Leave these pins unconnected if they are not used.

PCM_DIN	47	DI	PCM data input	VIL min=-0.3V; VIL max=0.45V; VIH min=1.6V; VIH max=2.1V	1.8V	
PCM_DOUT	49	DO	PCM data output	VOL max=0.45V; VOH min=1.35V	1.8V	
PCM_SYNC	51	IO	PCM synchronize signal	VOL max=0.45V; VOH min=1.35V; VIL min=-0.3V; VIL max=0.45V; VIH min=1.6V; VIH max=2.1V	1.8V	
Audio						
MIC_P	1	AI	Positive of audio input	Differential input	1.8 V	Leave them unconnected if it is not used.
MIC_N	3	AI	Negative of audio input			
SPK_P	5	AO	Positive of audio output	Differential output		Leave them unconnected if it is not used.
SPK_N	7	AO	Negative of audio output			
Other Pins						
LED_WWAN	42	OC	Network status indicator			Leave this pin unconnected if it is not used.
WAKEUP_IN	19	DI	Sleep mode control	V _{IL} min=-0.3V; V _{IL} max=0.45V; V _{IH} min=1.35V; V _{IH} max=2.1V	1.8V	Leave this pin unconnected if it is not used.

WAKEUP_OUT	32	DO	Sleep mode indicator		V _{OL} max=0.45V; V _{OH} min=1.35V	1.8V	Leave this pin unconnected if it is not used.
W_DISABLE	20	DI	Disable communication	RF	V _{IL} min=-0.3V; V _{IL} max=0.45V; V _{IH} min=1.35V; V _{IH} max=2.1V	1.8V	Leave this pin unconnected if it is not used.
NC	6, 13, 16, 17, 48		NC				Leave them unconnected. Do not use them.

3.2 Application Interfaces

This section introduces the reference design for main application interfaces.

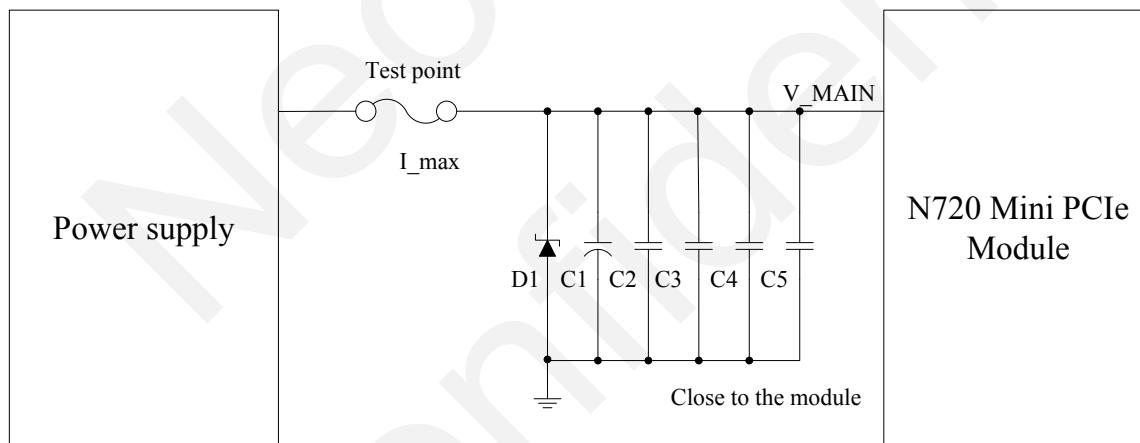
3.2.1 V_MAIN

Name	Pin	I/O	Function	Remarks
V_MAIN	2, 24, 39, 41, 52	PI	Main power supply input	3.0 V to 3.6 V (typical value: 3.3 V)

V_MAIN is the power supply input pin of the N720 Mini PCIe module. Its input voltage ranges from 3.0 V to 3.6 V and the typical value is 3.3 V. In addition to baseband, it supplies power to RF power amplifier and audio circuit. The performance of the V_MAIN power supply is a critical path to module's performance and stability. The input current at the V_MAIN pin will reach its peak of 3A when the signal is weak and the module works at the maximum transmitting power. The voltage will encounter a drop in such a situation. The module might restart if the voltage drops lower than 3.0 V.

The reference design of the V_MAIN power supply is shown as below:

Figure 3-2 Capacitors used for the power supply



In Figure 3-2, use TVS at D1 to enhance the performance of the module during a burst. SMF5.0AG ($V_{rwm}=5$ V& $P_{ppm}=200$ W) is recommended. A large bypass tantalum capacitor (220 μ F or 100 μ F) or aluminum capacitor (470 μ F or 1000 μ F) is expected at C1 to reduce voltage drops during bursts together with C2 (10 μ F ceramics capacitor). In addition, add 0.1 μ F, 100 pF, and 33 pF filter capacitors to enhance the stability of the power supply.

3.2.2 VREG_1V8

Name	Pin	I/O	Function	Remarks
VREG_1V8	11	PO	1.8 V power supply	Supply power for IO level shifting circuit. Leave this pin unconnected if it is not used.

VREG_1V8 outputs 1.8 V voltage. It is recommended that VREG_1.8 V@50 mA be used only for interface level.

3.2.3 PON_RESET

The PON_RESET pin is used to reset the module by hardware. Low level for more than 1 second at this pin triggers module reset. Figure 3-3 shows the reference design. If 1.8 V IO system is used to control the module reset, connect to this pin directly.

Figure 3-3 Reference design of hardware reset

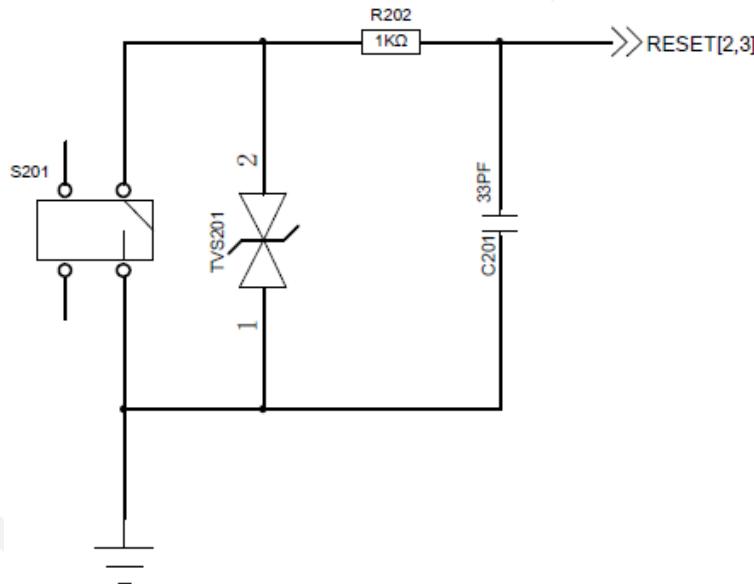


Figure 3-4 Reset control by external IO

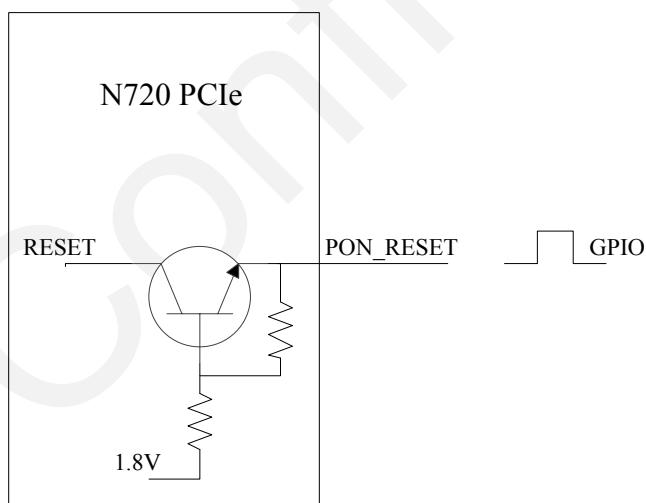
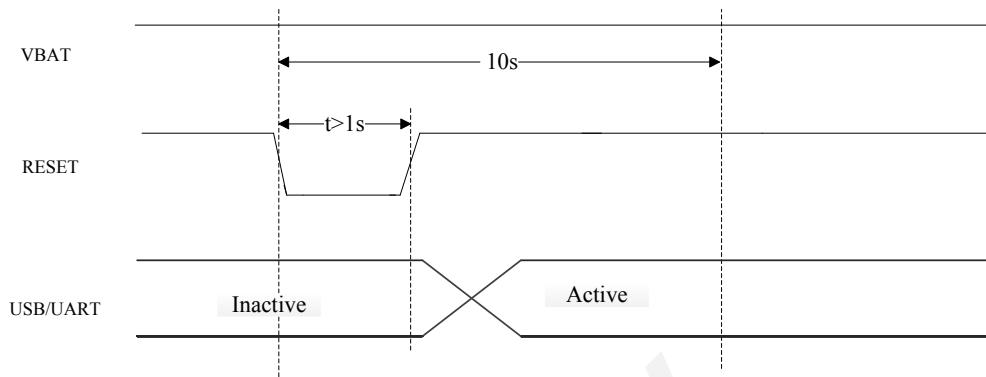


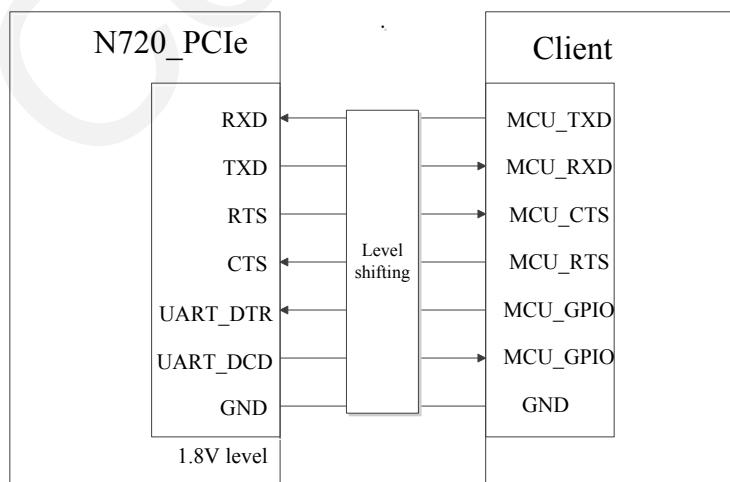
Figure 3-5 shows the reset sequence.

Figure 3-5 N720 PCIe reset sequence

3.2.4 UART

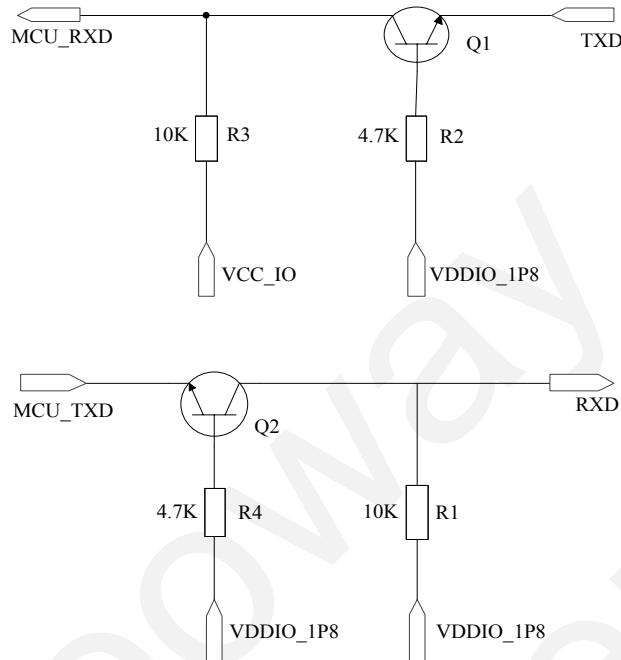
Name	Pin	I/O	Function	Remarks
UART_TX	31	DO	UART data transmit	Data transmission
UART_RX	23	DI	UART data receive	Data transmission
UART_CTS	28	DI	Clear to send	Leave this pin unconnected if it is not used.
UART_RTS	25	DO	Request to send	Leave this pin unconnected if it is not used.
UART_DTR	46	DI	Data terminal ready	Leave this pin unconnected if it is not used.
UART_DCD	30	DO	Data carrier detect	Leave this pin unconnected if it is not used.

N720 PCIe provides 1 group of UART interface, which supports hardware flow control and at the rate of 4 Mbps at most. The level at the interface is 1.8V. Figure 3-6 shows the reference design of the UART interface.

Figure 3-6 UART connection

If the UART does not match the logic voltage of the MCU, add a level shifting circuit outside of the module as shown in Figure 3-7 (for $V_{OL} \leq 200$ mV) and Figure 3-8 (for $V_{OL} > 200$ mV).

Figure 3-7 Recommended level shifting circuit 1



NOTE

Components:

R2/R4: 2K-10K. The greater the UART baud rate is, the lower the R2/R4 values are.

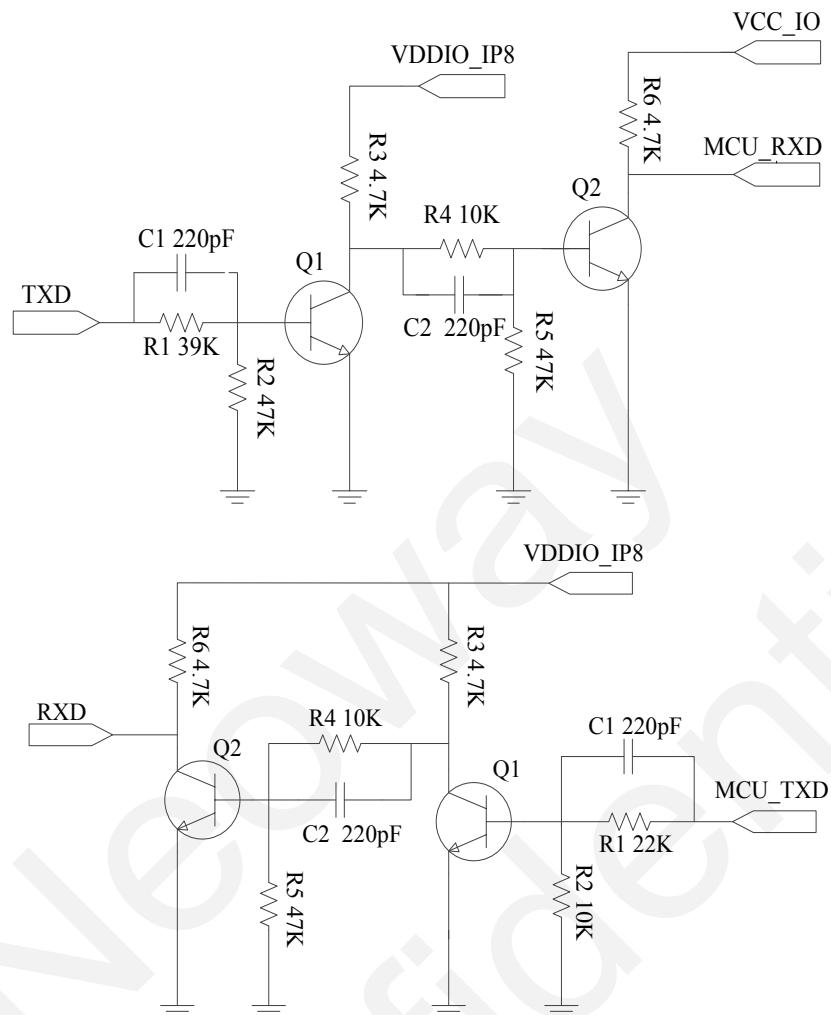
R1/R3: 4.7K-10K The greater the UART baud rate is, the lower the R/R3R3 value is.

Q1/Q2: MMBT3904 or MMBT2222. High-speed transistor is better.

MCU_RXD and MCU_TXD are respectively the TX and RX ports of the MCU while TXD and RXD are respectively the TX and RX ports of the module.

Voltage at VCC_IO is the voltage at the UART of the MCU while voltage at VDDIO_1V8 is the voltage at the UART of the module.

Figure 3-8 shows another recommended level shifting circuit.

Figure 3-8 Recommended level shifting circuit 2

NOTE

Components: Q1/Q2: MMBT3904 or MMBT2222. High-speed transistors are better.

MCU_TXD and MCU_RXD are respectively the TX and RX ports of the MCU, while TXD and RXD are respectively the TX and RX ports of the module.

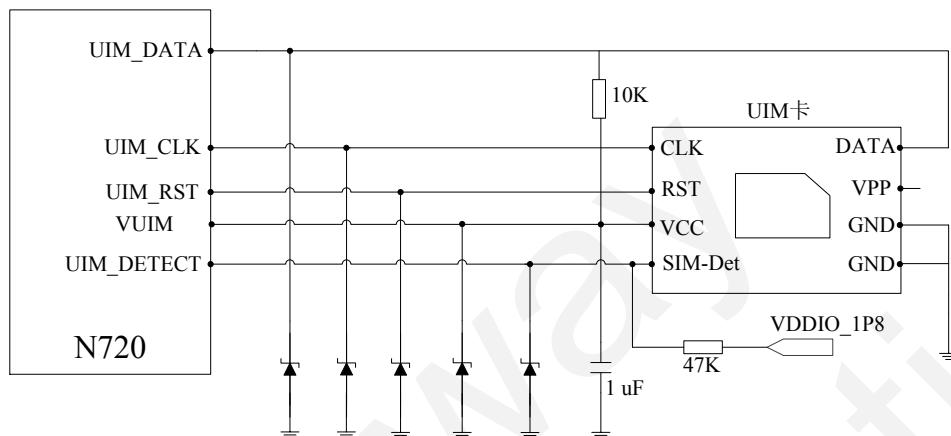
Voltage at VCC_IO is the voltage at the UART of the MCU while voltage at VDDIO_1V8 is the voltage at the UART of the module.

3.2.5 USIM

Name	Pin	I/O	Function	Remarks
V_USIM	8	PO	1.8V/3.3V	UIM power supply output
USIM_RST	14	DO	1.8V/3.3V	UIM reset
USIM_DATA	10	IO	1.8V/3.3V	UIM data input/output
USIM_CLK	12	DO	1.8V/3.3V	UIM clock
USIM_DETECT	44	DI	1.8V	UIM detect

N720 PCIe supports 1.8V/3V UIM cards. V_USIM is the power supply pin of the UIM card and its maximum load is 30 mA. The USIM_DATA pin is pulled up by 10 kΩ resistor internally, so an external pull-up resistor is not necessary in design. USIM_CLK is the clock signal pin, supporting 3.25 GHz of clock frequency. Figure 3-9 shows the reference design of the UIM card interface.

Figure 3-9 Reference design of SIM card interface



ESD protectors, such as ESD diodes or ESD varistors (with a junction capacitance of less than 33 pF), are recommended to be added on the SIM signals, especially in automotive or other applications with bad ESD. Replace the ESD diodes with 27 pF to 33 pF capacitors connecting to GND in common applications. The ESD diodes or small capacitors should be close to UIM card.

N720 PCIe supports SIM card detection. UIM_DETECT is a 1.8 V interrupt pin. Low level means UIM card detected while high level means no UIM card detected.



CAUTION

The antenna should be installed far away from the UIM card and UIM card traces, especially to the built-in antenna.

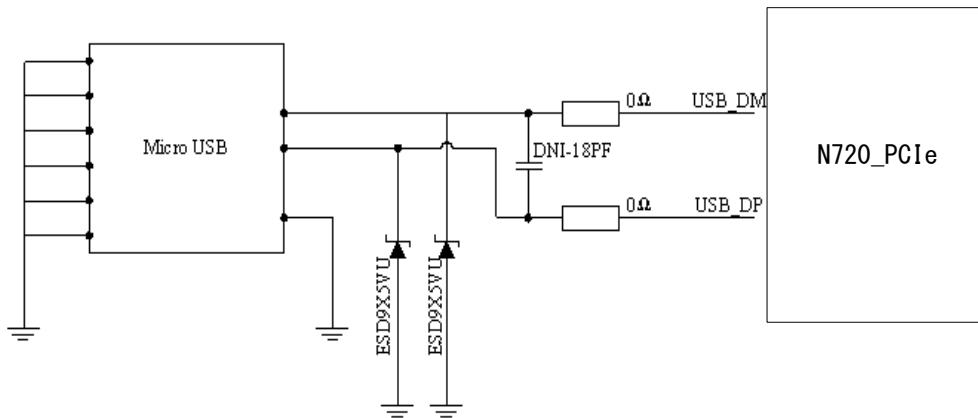
The UIM traces on the PCB should be as short as possible and shielded with GND copper.

The ESD protection diodes or small capacitors should be close to UIM card on the PCB.

3.2.6 USB

Name	Pin	I/O	Function	Remarks
USB_D-	36	IO	negative signal of USB data	Used for firmware download and data transmission
USB_D+	38	IO	positive signal of USB data	Differential trace 90Ω impedance

USB can be used for firmware download, data communication, and commissioning. Figure 3-10 shows the recommended USB circuit.

Figure 3-10 Recommended resign of USB circuit

The junction capacitance of the TVS protection diodes for USB_D+ and USB_D- should be lower than 12 pF as possible. USB data lines adopt differential trace design, in which the differential impedance is limited to 90 Ω characteristic impedance. Isolate the traces from other signal traces.

3.2.7 PCM

Name	Pin	I/O	Function	Level	Remarks
PCM_CLK	45	IO	PCM clock signal	1.8V	Leave these pins unconnected if they are not used.
PCM_DIN	47	DI	PCM data input	1.8V	
PCM_DOUT	49	DO	PCM data output	1.8V	
PCM_SYNC	51	IO	PCM synchronize	1.8V	

N720 PCIe provides one PCM interface that supports host and client device mode. The reference level at the interface is 1.8 V.

The following figures shows the PCM sequence and connection.

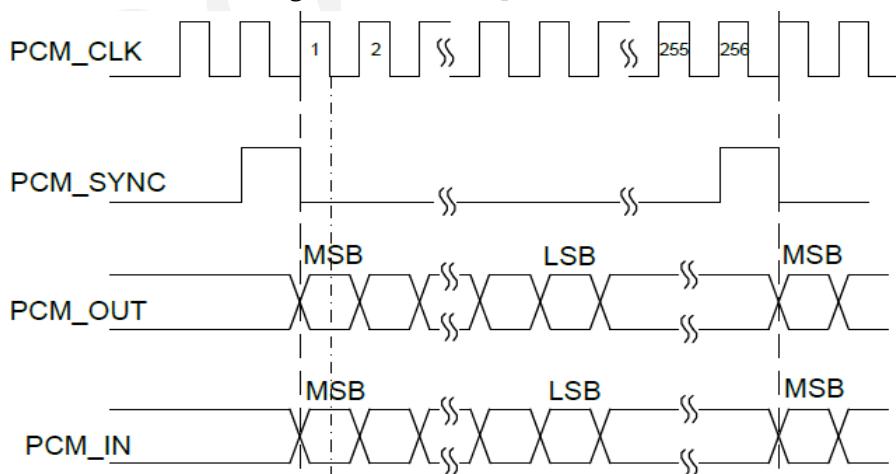
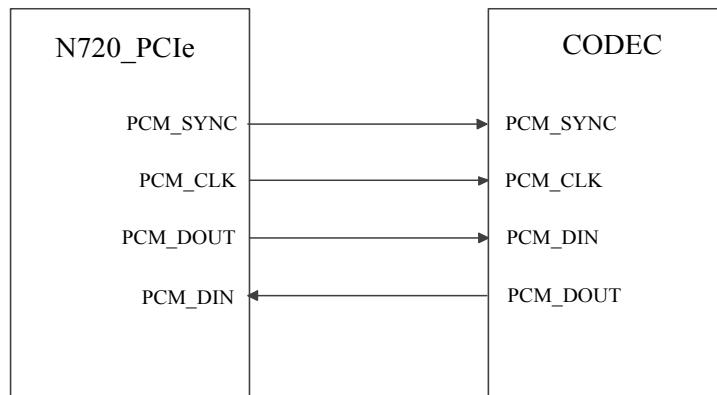
Figure 3-11 PCM sequence

Figure 3-12 PCM connection

3.2.8 Analog Audio

Name	Pin	I/O	Function	Level Feature	Remarks
MIC_P	1	AI	Negative of audio output	Differential input	Leave these pins unconnected if they are not used.
MIC_N	3	AI	Positive of audio output	differential input	Leave these pins unconnected if they are not used.
SPK_P	5	AO	Positive of audio output	differential input	Leave these pins unconnected if they are not used.
SPK_N	7	AO	Negative of audio output		

MIC_P and MIC_N are used for differential MIC input. Electret MIC is recommended.

SPK_P and SPK_N are used for differential speaker or receiver output. An audio amplifier is required.

On the PCB board, bead, filter capacitor, and ESD components should be as closer to the audio components or pins as possible. The trace should be far away from interference sources and as shorter as possible. The differential traces should comply with the design rules.

The volume of MIC and SPK can be adjusted via API commands. For details, see

Neoway_N720_Command_Manual.

No bias circuit is required externally because there is a bias voltage for the electret MIC in the module.

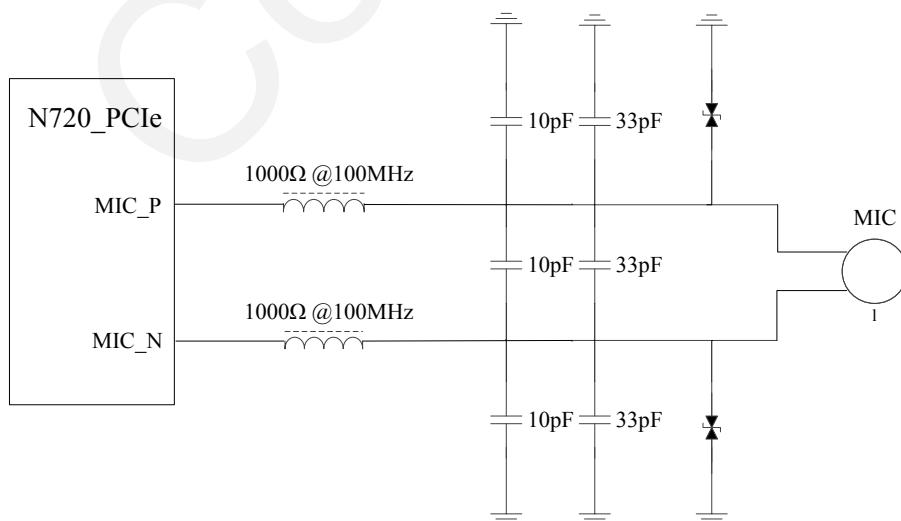
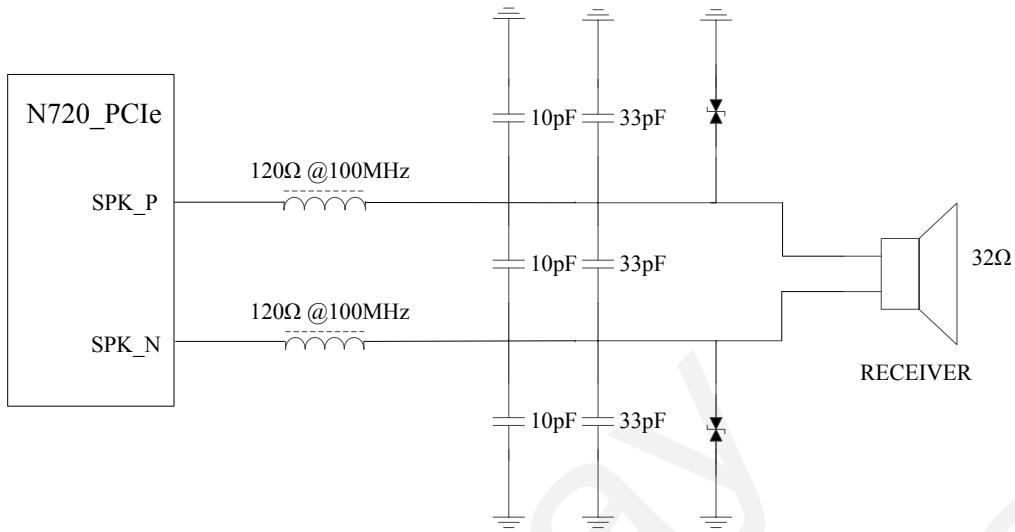
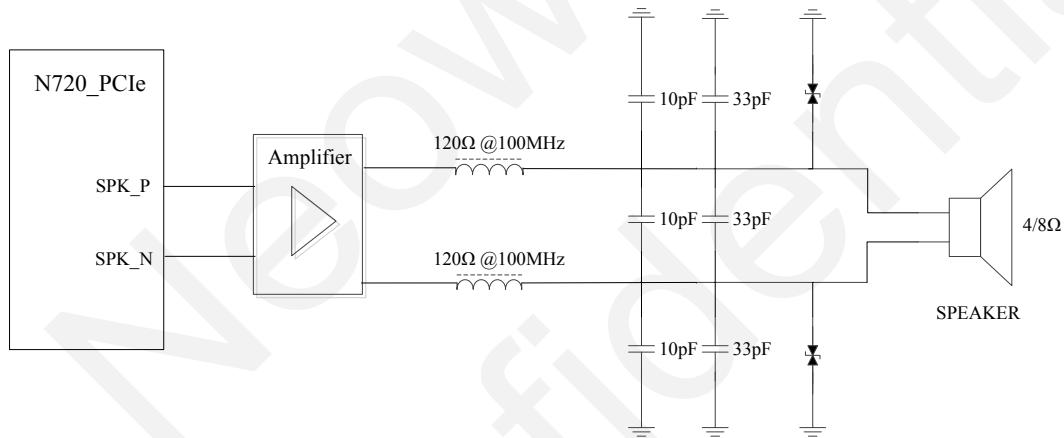
Figure 3-13 Reference MIC design

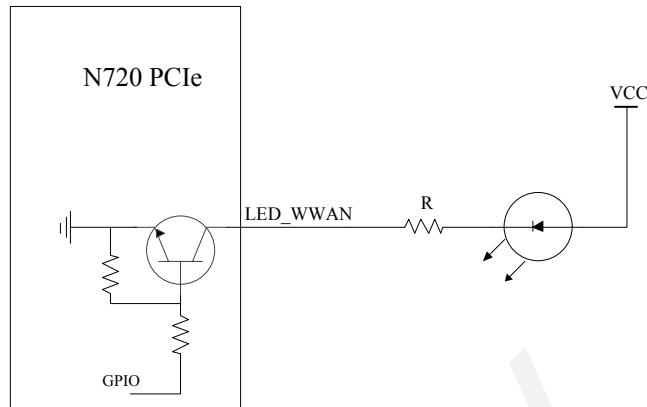
Figure 3-14 Reference receiver design**Figure 3-15** Reference speaker design

3.2.9 Other Interfaces

Name	Pin	I/O	Function	Level Feature	Remarks
LED_WWAN	42	OC	Network status indicator		OC
WAKEUP_IN	19	DI	Sleep mode control	1.8V	
WAKEUP_OUT	32	DO	Sleep mode indicator	1.8V	
W_DISABLE	20	DI	Disable RF communication	1.8V	

LED_WWAN

The LED_WWAN interface uses an OC output and the maximum input current reaches 20 mA. Connect a resistor in series when connecting an LED. The resistance can be adjusted according to the brightness of the LED. The LED is glowed when low level is at the LED_WWAN pin.

Figure 3-16 LED_WWAN reference design

WAKEUP_IN and WAKEUP_OUT

The WAKEUP_IN pin is used to control sleep mode together with AT commands. Enable the sleep mode function by AT command. Then pulling WAKEUP_IN low will bring the module into sleep mode if the module is idle. In this mode, the idle current is less than 4 mA, depending on the DRX setting of network. In sleep mode, the module can respond to the incoming call, SMS, and data. The host MCU can also control the module to exit sleep mode by controlling WAKEUP_IN.

Process of entering sleep mode:

1. Keep WAKEUP_IN high level in normal working mode. Activate the sleep mode by using the **AT+ENPWRSAVE=1** command.
2. Pull WAKEUP_IN low, and the module will enter sleep mode, but only after process and pending data finished.
3. In sleep mode, the external MCP can pull WAKEUP_IN high so that the module will exit from sleep mode actively. Then the module can transmit data and initiate calls. After processing is finished, pull WAKEUP_IN low again to take the module back to sleep mode.
4. In sleep mode, the module can be woken up by the events of incoming voice call, received data, or SMS. Meanwhile the module will send out the unsolicited messages through the UART.

Upon receipt of the unsolicited messages, the host MCU should pull WAKEUP_IN high firstly, otherwise the module will resume sleep mode in two minutes after the service processing. Then the host MCU can process the voice call, received data, or SMS. After processing is finished, pull WAKEUP_IN low again to put the module into sleep mode.

The WAKEUP_OUT pin is used to indicate whether the module is in sleep mode.

W_DISABLE

The W_DISABLE pin is used to disable the RF communication of the module. It works with software support.

4 Antenna Interfaces

4.1 Interface Types

N720_Pcie module provides three interfaces respectively for 2G/3G/4G main antenna, 4G diversity antenna, and GNSS antenna. Figure 4-1 shows their positions on the PCIe module.

Figure 4-1 N720_Pcie antenna interfaces

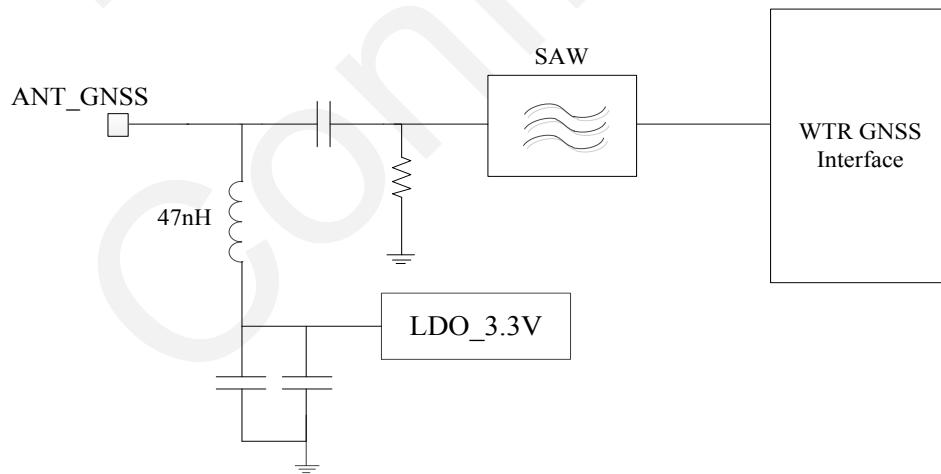


Antennas connecting to the module must comply with mobile device standards: a VSWR ranging from 1.1 to 1.5 and $50\ \Omega$ impedance. The antennas should be well matched to achieve the best performance. They should be installed far away from high-speed logic circuits, DC/DC power or any other strong disturbing sources.

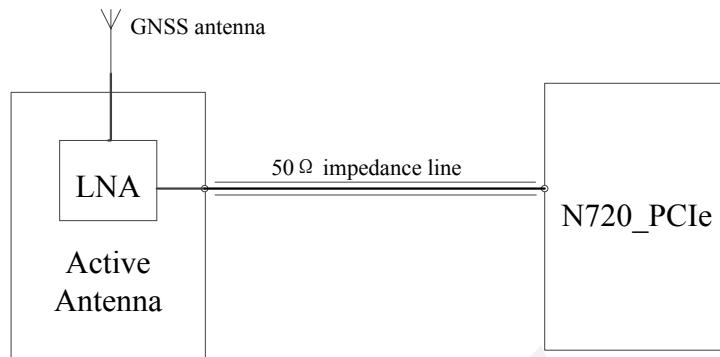
4.2 GNSS Antenna

Figure 4-2 shows the circuit of GNSS RF inside the N720 Mini PCIe module.

Figure 4-2 Internal GNSS RF circuit

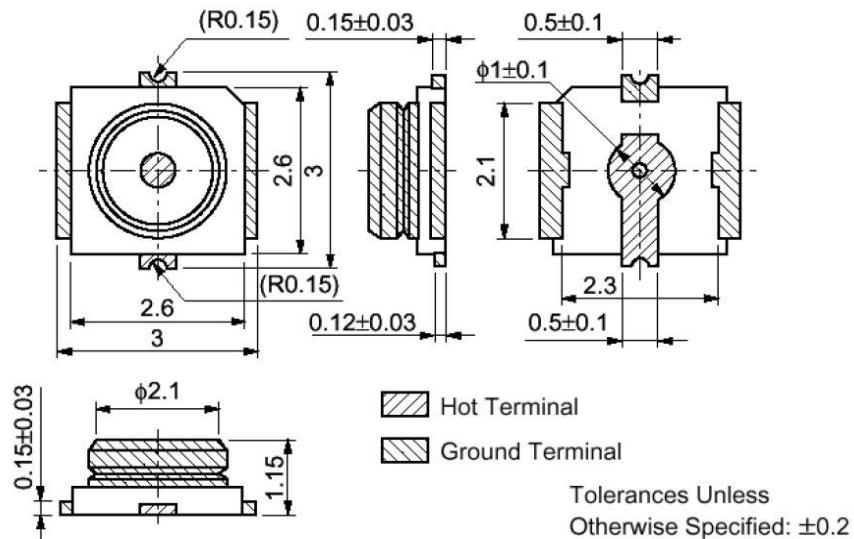


If the GNSS signal is poor, the electric signal converted will be very poor and easy to get interference. So, an active antenna is recommended. The poor signal that the active GNSS antenna receives will be amplified by an LNA and then transmitted to the internal IC through the feeder. The N720 Mini PCIe module supplies 3.3 V power for the active antenna internally and connects to it through a 47 nH inductor. The GNSS antenna can be an active ceramic antenna.

Figure 4-3 Active antenna connection

4.3 RF Connector

To adopt RF antenna connections, the GSC RF connector MM9329-2700RA1 from Murata is recommended. Figure 4-4 shows the encapsulation specifications.

Figure 4-4 Encapsulation specifications of Murata RF connector

5 Electrical Features and Reliability

5.1 Temperature

Table 5-1 Temperature feature

Module Status	Minimum Value	Typical Value	Maximum Value
Work	-40 °C	25 °C	85 °C
Storage	-45 °C		90 °C



CAUTION

If the module works in temperature exceeding the thresholds, some of its RF performance indicators might be worse but it can still work properly.

5.2 Working Band

Table 5-2 N720 Mini PCIe working band

Working Band	Uplink	Downlink
GSM850	824~849 MHz	869~894 MHz
EGSM900	880~915 MHz	925~960 MHz
DCS1800	1710~1785 MHz	1805~1880 MHz
PCS1900	1850~1910 MHz	1930~1990 MHz
CDMA BC0	824~849 MHz	869~894 MHz
UMTS B1	1920~1980 MHz	2110~2170 MHz
UMTS B2	1850~1910 MHz	1930~1990 MHz
UMTS B4	1710~1755 MHz	2110~2155 MHz
UMTS B5	824~849 MHz	869~894 MHz
UMTS B8	880~915 MHz	925~960 MHz
UMTS B9	1749.9~1784.9 MHz	1844.9~1879.9 MHz
UMTS B19	869~894 MHz	869~894 MHz
TD-SCDMA B34	2010~2025 MHz	2010~2025 MHz
TD-SCDMA B39	1880~1920 MHz	1880~1920 MHz
FDD-LTE B1	1920~1980 MHz	2110~2170 MHz
FDD-LTE B2	1850~1910 MHz	1930~1990 MHz
FDD-LTE B3	1710~1785 MHz	1805~1880 MHz

FDD-LTE B4	1710~1755 MHz	2110~2155 MHz
FDD-LTE B5	824~849 MHz	869~894 MHz
FDD-LTE B7	2500~2570 MHz	2620~2690 MHz
FDD-LTE B8	880~915MHz	925~960 MHz
FDD-LTE B9	1749.9~1784.9MHz	1844.9~1879.9 MHz
FDD-LTE B12	699~716 MHz	728~746 MHz
FDD-LTE B17	704~716 MHz	734~746 MHz
FDD-LTE B19	830~845 MHz	875~890 MHz
FDD-LTE B20	832~862 MHz	791~821 MHz
FDD-LTE B28	703~748 MHz	758~803 MHz
TDD-LTE B38	2570~2620 MHz	2570~2620 MHz
TDD-LTE B39	1880~1920 MHz	1880~1920 MHz
TDD-LTE B40	2300~2400 MHz	2300~2400 MHz
TDD-LTE B41	2555~2655 MHz	2555~2655 MHz

5.3 TX Power and RX Sensitivity

Table 5-3 N720 Mini PCIe RF power and RX sensitivity

Band	Transmitting Power	Receiving Sensitivity
GSM850	33dBm+2/-2 dBm	<-108 dBm
EGSM900	33dBm+2/-2 dBm	<-108 dBm
DCS1800	30dBm+2/-2 dBm	<-108 dBm
PCS1900	30dBm+2/-2 dBm	<-108 dBm
CDMA BC0	24dBm +1/-1 dBm	<-107 dBm
UMTS B1	24dBm +1/-3 dBm	<-108 dBm
UMTS B2	24dBm +1/-3 dBm	<-108 dBm
UMTS B4	24dBm +1/-3 dBm	<-108 dBm
UMTS B5	24dBm +1/-3 dBm	<-108 dBm
UMTS B8	24dBm +1/-3 dBm	<-108 dBm
UMTS B9	24dBm +1/-3 dBm	<-108 dBm
UMTS B19	24dBm +1/-3 dBm	<-108 dBm
TD-SCDMA B34	24dBm +1/-3 dBm	<-109 dBm
TD-SCDMA B39	24dBm +1/-3 dBm	<-109 dBm
FDD-LTE B1 (10MHz)	23dBm+2/-2 dBm	<-97 dBm

FDD-LTE B2 (10MHz)	23dBm+2/-2 dBm	<-95 dBm
FDD-LTE B3 (10MHz)	23dBm+2/-2 dBm	<-95 dBm
FDD-LTE B4(10MHz)	23dBm+2/-2 dBm	<-97 dBm
FDD-LTE B5(10MHz)	23dBm+2/-2 dBm	<-95 dBm
FDD-LTE B7(10MHz)	23dBm+2/-2 dBm	<-95 dBm
FDD-LTE B8(10MHz)	23dBm+2/-2 dBm	<-95 dBm
FDD-LTE B9(10MHz)	23dBm+2/-2 dBm	<-96 dBm
FDD-LTE B12(10MHz)	23dBm+2/-2 dBm	<-95 dBm
FDD-LTE B17(10MHz)	23dBm+2/-2 dBm	<-95 dBm
FDD-LTE B20(10MHz)	23dBm+2/-2 dBm	<-95 dBm
FDD-LTE B28(10MHz)	23dBm+2/-2 dBm	<-95 dBm
TDD-LTE B38(10MHz)	23dBm+2/-2 dBm	<-97 dBm
TDD-LTE B39(10MHz)	23dBm+2/-2 dBm	<-97 dBm
TDD-LTE B40(10MHz)	23dBm+2/-2 dBm	<-97 dBm
TDD-LTE B41(10MHz)	23dBm+2/-2 dBm	<-95 dBm

 NOTE

All the values above are obtained in the lab environment. In actual applications, there might be a difference because of the network environment.

5.4 EMI/EMC Features

Table 5-4 ESD features

Testing Point	Contact Discharge	Air Discharge
V_MAIN	±8 kV	±15 kV
GND	±8 kV	±15 kV
ANT	±8 kV	±15 kV
Cover	±8 kV	±15 kV
Others	±2 kV	±4 kV

 NOTE

When using the N720 Mini PCIe module, ensure that the ground near the fixing holes connects to that of the device to avoid module damage caused by ESD.

6 Mechanical Feature

6.1 Dimensions

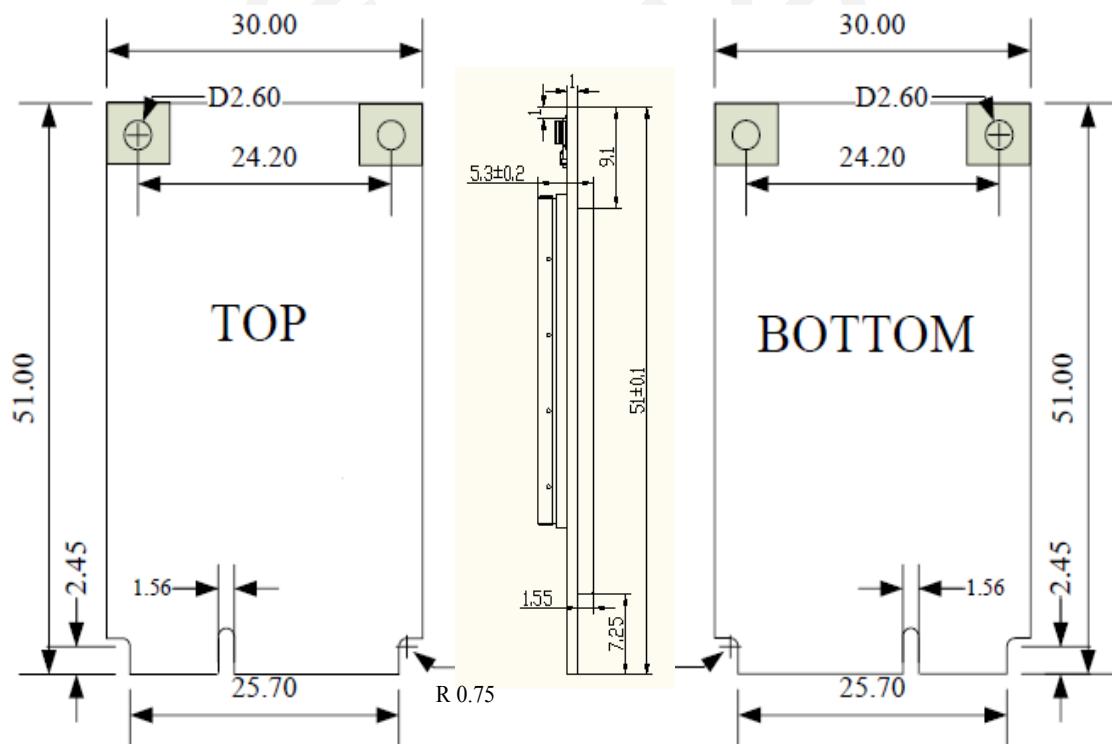
Table 6-1 N720 dimensions

Specifications	N720
Dimensions	(28±0.1) mm x (30±0.1) mm x (2.8±0.1) mm (H x W x D)
Weight	5.1g
Package	100-Pin LGA

Table 6-2 N720 Mini PCIe dimensions

Specifications	N720 Mini PCIe
Dimensions	(30±0.1)mm* (51±0.1) mm* (5.3±0.15)mm (H*W*D)
Weight	11.2g
Package	52-Pin Mini PCIe

Figure 6-1 N720 Mini PCIe dimensions



6.2 N720 Mini PCIe Pictures

Figure 6-2 Top view of N720 Mini PCIe



Figure 6-3 Bottom view of N720 Mini PCIe



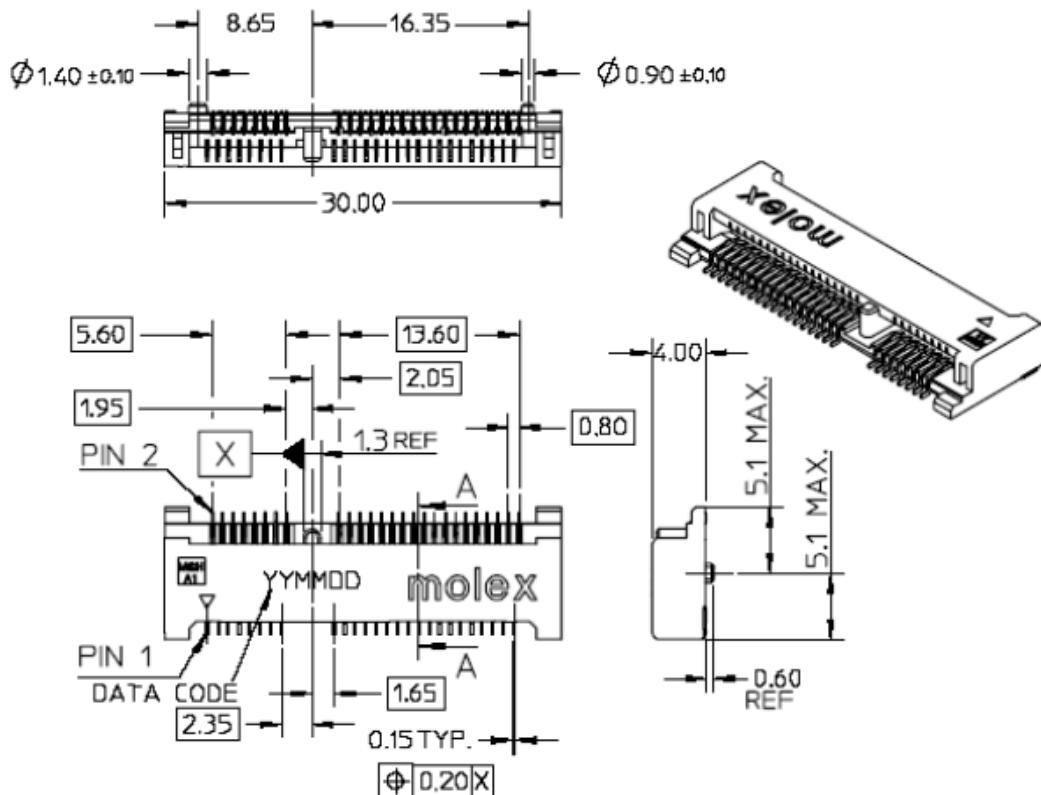
CAUTION

The color of the PCB board in the above figures will not be the acceptance criteria.

7 Mounting

The N720 Mini PCIe module complies with PCI Express Mini Card 1.2 standard. It is mounted onto the Mini PCIe card connector by plugging in directly. The following figure shows the dimensions of Mini PCIe connector 679100002 from Molex.

Figure 7-1 Mini PCIe card connector



8 Packaging and Storage

8.1 Packaging

N720 Mini PCIe modules are packaged using EPE foam tray together with desiccant and humidity indicating card on delivery to guarantee a long shelf life.

Figure 8-1 N720 Mini PCIe packaging



Figure 8-2 Shipment packaging



8.2 Storage

Storage temperature: 20°C~26°C

Storage humidity: 40%-60%

Storage date: 120 days